

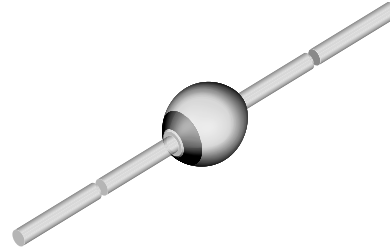
Ultra Fast Avalanche Sinterglass Diode

Features

- Glass passivated
- Hermetically sealed axial leaded glass envelope
- Low reverse current
- High reverse voltage

Applications

Switched mode power supplies
High-frequency inverter circuits



949539

Mechanical Data

Case: Sintered glass case, SOD 57

Terminals: Plated axial leads, solderable per MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Mounting Position: Any

Weight: 370 mg, (max. 500 mg)

Parts Table

Part	Type differentiation	Package
SF4001	$V_R = 50 \text{ V}; I_{FAV} = 1 \text{ A}$	SOD57
SF4002	$V_R = 100 \text{ V}; I_{FAV} = 1 \text{ A}$	SOD57
SF4003	$V_R = 200 \text{ V}; I_{FAV} = 1 \text{ A}$	SOD57
SF4004	$V_R = 400 \text{ V}; I_{FAV} = 1 \text{ A}$	SOD57
SF4005	$V_R = 600 \text{ V}; I_{FAV} = 1 \text{ A}$	SOD57
SF4006	$V_R = 800 \text{ V}; I_{FAV} = 1 \text{ A}$	SOD57
SF4007	$V_R = 1000 \text{ V}; I_{FAV} = 1 \text{ A}$	SOD57

Absolute Maximum Ratings

$T_{amb} = 25 \text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Test condition	Sub type	Symbol	Value	Unit
Reverse voltage = Repetitive peak reverse voltage	see electrical characteristics	SF4001	$V_R = V_{RRM}$	50	V
	see electrical characteristics	SF4002	$V_R = V_{RRM}$	100	V
	see electrical characteristics	SF4003	$V_R = V_{RRM}$	200	V
	see electrical characteristics	SF4004	$V_R = V_{RRM}$	400	V
	see electrical characteristics	SF4005	$V_R = V_{RRM}$	600	V
	see electrical characteristics	SF4006	$V_R = V_{RRM}$	800	V
	see electrical characteristics	SF4007	$V_R = V_{RRM}$	1000	V

Parameter	Test condition	Sub type	Symbol	Value	Unit
Peak forward surge current	$t_p = 10$ ms, half sinewave		I_{FSM}	30	A
Average forward current	Lead length $l = 10$ mm		I_{FAV}	1	A
Junction and storage temperature range			$T_j = T_{stg}$	-55 to +175	°C
Non repetitive reverse avalanche energy	$I_{(BR)R} = 0.4$ A		E_R	10	mJ

Maximum Thermal Resistance

$T_{amb} = 25$ °C, unless otherwise specified

Parameter	Test condition	Sub type	Symbol	Value	Unit
Junction ambient	Lead length $l = 10$ mm, $T_L = \text{constant}$		R_{thJA}	45	K/W
	on PC board neith spacing 25 mm		R_{thJA}	100	K/W

Electrical Characteristics

$T_{amb} = 25$ °C, unless otherwise specified

Parameter	Test condition	Sub type	Symbol	Min	Typ.	Max	Unit
Forward voltage	$I_F = 1$ A	SF4001-SF4004	V_F			1	V
	$I_F = 1$ A	SF4005-SF4007	V_F			1.7	V
Reverse current	$V_R = V_{RRM}$		I_R			5	μA
	$V_R = V_{RRM}, T_j = 125$ °C		I_R			50	μA
Reverse breakdown voltage	$I_R = 100$ μA	SF4001	$V_{(BR)R}$	50			V
	$I_R = 100$ μA	SF4002	$V_{(BR)R}$	100			V
	$I_R = 100$ μA	SF4003	$V_{(BR)R}$	200			V
	$I_R = 100$ μA	SF4004	$V_{(BR)R}$	400			V
	$I_R = 100$ μA	SF4005	$V_{(BR)R}$	600			V
	$I_R = 100$ μA	SF4006	$V_{(BR)R}$	800			V
	$I_R = 100$ μA	SF4007	$V_{(BR)R}$	1000			V
Reverse recovery time	$I_F = 0.5$ A, $I_R = 1$ A, $i_R = 0.25$ A	SF4001-SF4004	t_{rr}			50	ns
	$I_F = 0.5$ A, $I_R = 1$ A, $i_R = 0.25$ A	SF4005-SF4007	t_{rr}			75	ns

Typical Characteristics ($T_{amb} = 25$ °C unless otherwise specified)

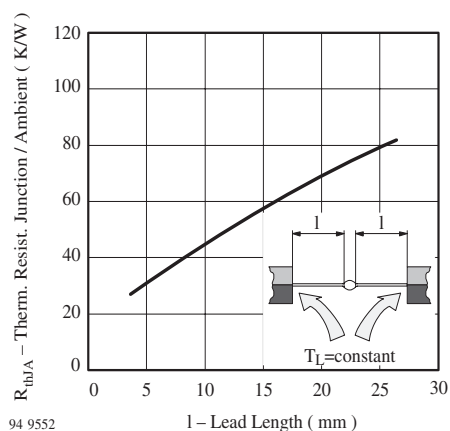


Figure 1. Max. Thermal Resistance vs. Lead Length

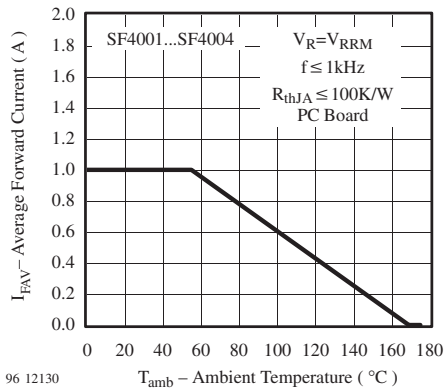


Figure 2. Max. Average Forward Current vs. Ambient Temperature

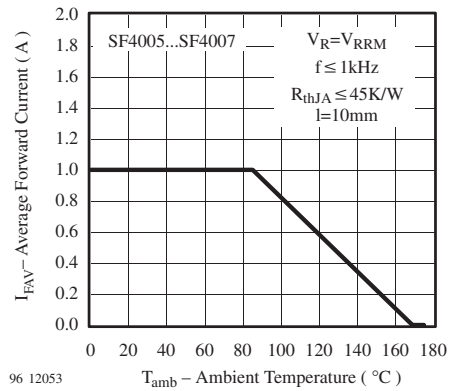


Figure 5. Max. Average Forward Current vs. Ambient Temperature

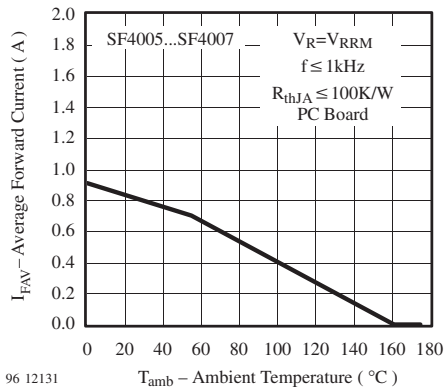


Figure 3. Max. Average Forward Current vs. Ambient Temperature

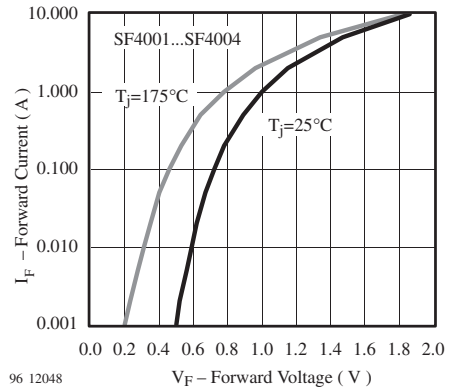


Figure 6. Max. Forward Current vs. Forward Voltage

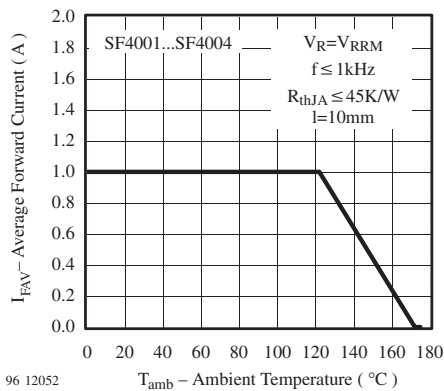


Figure 4. Max. Average Forward Current vs. Ambient Temperature

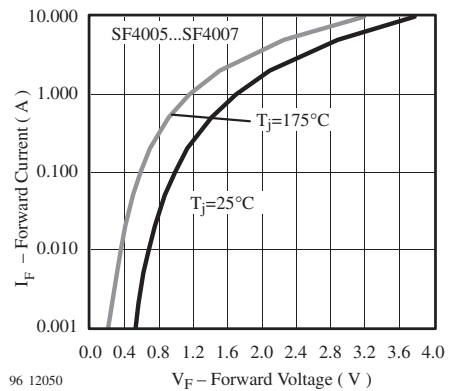
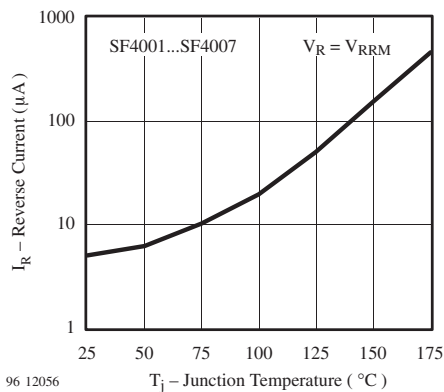
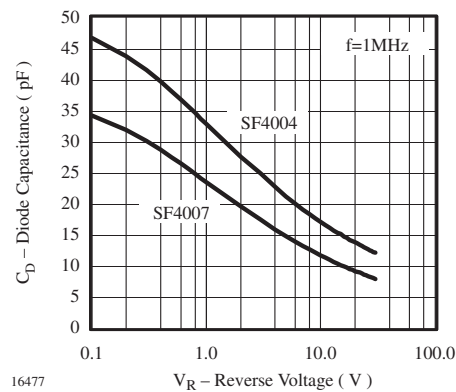


Figure 7. Max. Forward Current vs. Forward Voltage



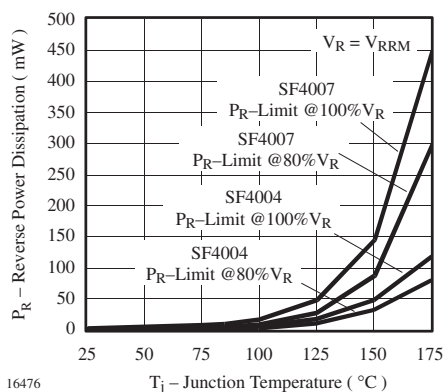
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Figure 8. Max. Reverse Current vs. Junction Temperature



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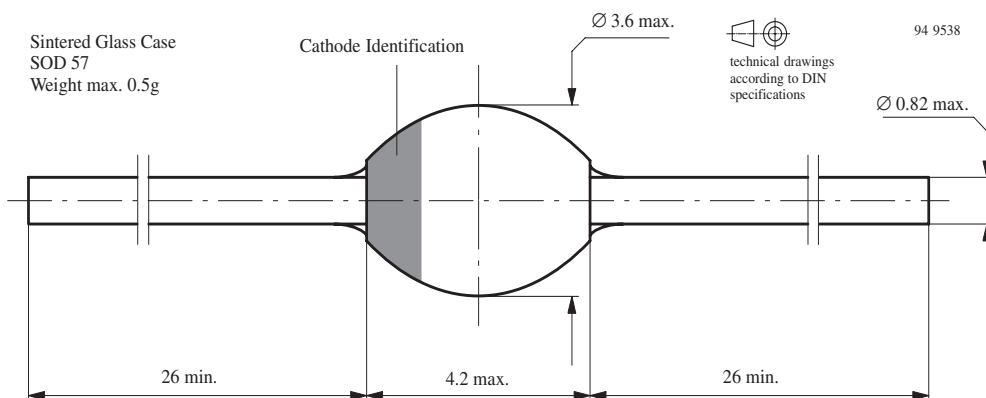
Figure 10. Diode Capacitance vs. Reverse Voltage



16476

Figure 9. Max. Reverse Power Dissipation vs. Junction Temperature

Package Dimensions in mm





Ozone Depleting Substances Policy Statement

It is the policy of **Vishay Semiconductor GmbH** to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

**We reserve the right to make changes to improve technical design
and may do so without further notice.**

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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